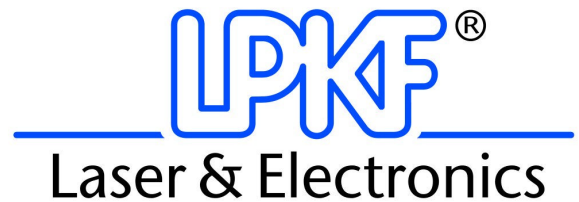


FOR IMMEDIATE RELEASE

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New Electronic Layout Thanks to 3D Components

June 2009, Garbsen, Germany – The MID (Molded Interconnect Devices) division has been a major contributor to the positive performance of LPKF Laser & Electronics AG this year. Three dimensional components combine mechanical and electronic functions – and open up new opportunities for electronics design engineers to create compact and economical product layouts. A new brochure is now available which describes several currently successful 3D MID projects and innovative areas of application.

“Millions of three dimensional electronics components are produced every month in electronics factories – and many of them are made using the patented LDS method,” says Nils Heining, MID Division Manager at LPKF, with satisfaction in the light of the strong demand for high performance laser structuring systems. In the LDS (Laser Direct Structuring) method, a laser beam activates specific areas of injection-molded plastic components. The electrical structures created in this way are metalized in an electroless plating process. These components boast many advantages: they decrease the number of parts required, reduce assembly work, and save space. The twelve page brochure attractively shows product examples, and can be downloaded free of charge at: <http://www.lpkfusa.com/mid/>



About LPKF

LPKF Laser & Electronics AG manufactures machines and laser systems used in electronics fabrication, medical technology, the automotive sector, and the production of solar cells. Around 20 percent of the workforce is engaged in research and development.

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